±15kV ESD-Protected, Single/Dual/Octal, CMOS Switch Debouncers

Absolute Maximum Ratings

Voltage (with respect to GND)	6-Pin SOT23 (derate 8.7mW/°C above +70°C)691mW
V _{CC} 0.3V to +	-6V 20-Pin SSOP (derate 8.0mW/°C above +70°C)640mW
IN_ (Switch Inputs)30V to +3	Operating Temperature Range
EN0.3V to +	-6V E Suffix40°C to +125°C
OUT_, CH 0.3V to (V _{CC} + 0.3	3V) M Suffix55°C to +125°C
OUT Short-Circuit Duration	Storage Temperature Range65°C to +160°C
(One or Two Outputs to GND)Continuo	bus Lead Temperature (soldering, 10s)+300°C
Continuous Power Dissipation (T _A = +70°C)	Soldering Temperature (reflow)
4-Pin SOT143 (derate 4.0mW/°C above +70°C)	+260°C
320mW	Containing lead+240°C

Stresses beyond those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated in the operational sections of the specifications is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.

Electrical Characteristics

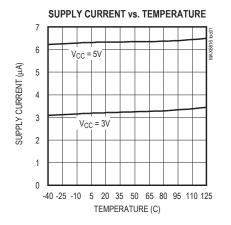
 $(V_{CC}$ = +2.7V to +5.5V, T_A = T_{MIN} to T_{MAX} , unless otherwise noted. Typical values are at V_{CC} = +5V, T_A = +25°C.) (Note 1)

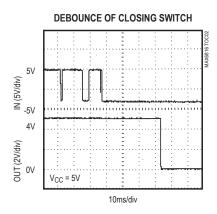
PARAMETER	SYMBOL	CONDITIONS		MIN	TYP	MAX	UNITS	
Operating Voltage Range	Vcc					5.5	V	
Supply Current	Icc	VC	V _{CC} = 5V, I _{OUT} = 0A, IN_ = V _{CC}		6	20	μA	
Debounce Duration		MA	MAX6818EAP		40	80	ms	
	t _{DP}	MAX6816EUS/MAX6817EUT		20	50	80		
		MAX	MAX6817MUT		50	90		
	VIL					0.8	V	
Input Threshold	VIH	VC	V _{CC} = 5V				\ \ \ \ \ \ \ \ \ \ \ \ \ \ \ \ \ \ \	
	VIΠ	VC	C = 2.7V	2.0			V	
Input Hysteresis					300		mV	
Input Pullup Resistance				32	63	100	kΩ	
IN Input Current	IIN	V _{IN}	= ±15V			±1	mA	
Input Voltage Range	VIN					+25	V	
Undervoltage-Lockout Threshold					1.9	2.6	V	
OUT CH Output Voltage	Vol	I _{SINK} = 1.6mA				0.4	V	
OUT_, CH Output Voltage	Voн	I _{SOURCE} = 0.4mA		V _{CC} - 1.0		V		
EN Pulse Width	tEN						ns	
EN Threshold		V _{CC} = 5V		8.0	1.7	2.4	_V	
Livinieshold		VC	C = 2.7V	8.0	1.1	2.0	V	
EN Input Current	Iμ					±1	μA	
EN Low to Out Active Propagation Delay	tpE	RL	$R_L = 10k\Omega, C_L = 100pF$			100	ns	
EN High to Out Three-State Propagation Delay	tPD	$R_L = 1k\Omega$, $C_L = 15pF$				100	ns	
ENLow to CH Out High Propagation Delay	tPC	$R_L = 10k\Omega$, $C_L = 50pF$				100	ns	
OUT_Three-State Leakage Current		V _{OUT} = 0V or V _{CC}				±10	μA	
ESD CHARACTERISTICS								
			IEC 1000-4-2 Air-Gap Discharge		±15			
ESD Protection		IN_	IEC 1000-4-2 Contact Discharge		±8		kV	
			Human Body Model		±15			

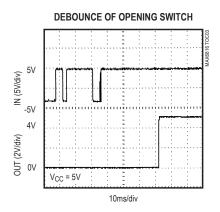
Note 1: MAX6816 and MAX6817 production testing is done at T_A = +25°C; overtemperature limits are guaranteed by design.

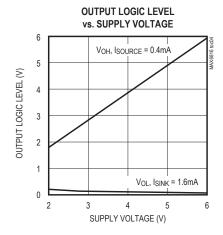
Typical Operating Characteristics

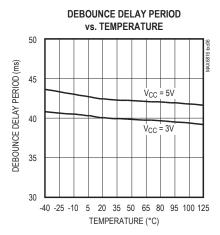
(TA = +25°C, unless otherwise noted.)

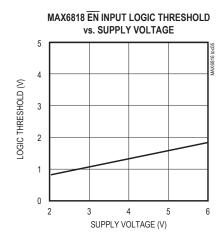


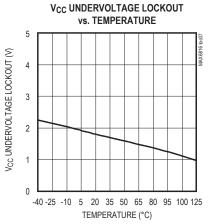




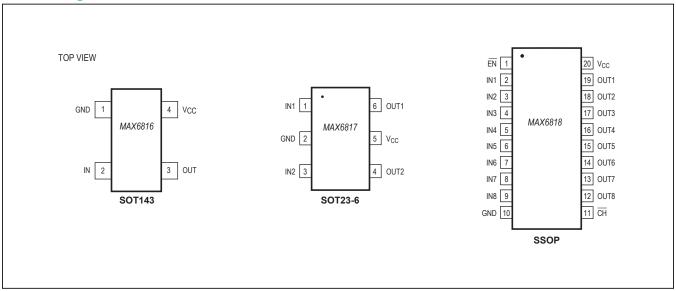








Pin Configurations



Pin Description

PIN			NABAT	FUNCTION	
MAX6816	MAX6817	MAX6818	NAME	FUNCTION	
1	2	10	GND	Ground	
2	_	_	IN	Switch Input	
_	1, 3	_	IN1, IN2	Switch Inputs	
_	_	2–9	IN1–IN8	Switch Inputs	
3	_	_	OUT	CMOS Debounced Output	
_	4, 6	_	OUT2, OUT1	CMOS Debounced Outputs	
_	_	12–19	OUT8-OUT1	CMOS Debounced Outputs	
4	5	20	Vcc	+2.7V to +5.5V Supply Voltage	
_	_	1	ĒN	Active-Low, Three-State Enable Input for outputs. Resets $\overline{\text{CH}}$. Tie to GND to "always enable" outputs.	
_	_	11	СН	Change-of-State Output. Goes low on switch input change of state. Resets on EN. Leave unconnected if not used.	

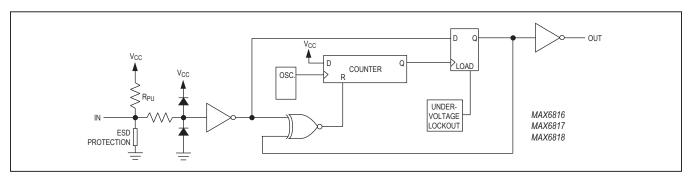


Figure 1. Block Diagram

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Detailed Description

Theory of Operation

The MAX6816/MAX6817/MAX6818 are designed to eliminate the extraneous level changes that result from interfacing with mechanical switches (switch bounce). Virtually all mechanical switches bounce upon opening or closing. These switch debouncers remove bounce when a switch opens or closes by requiring that sequentially clocked inputs remain in the same state for a number of sampling periods. The output does not change until the input is stable for a duration of 40ms.

The circuit block diagram (Figure 1) shows the functional blocks consisting of an on-chip oscillator, counter, exclusive-NOR gate, and D flip-flop. When the input

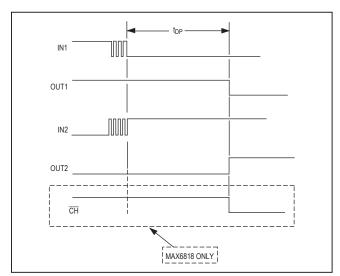


Figure 2. Input Characteristics

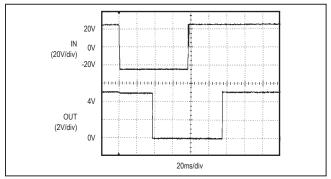


Figure 3. Switch Input ±25V Fault Tolerance

does not equal the output, the XNOR gate issues a counter reset. When the switch input state is stable for the full qualification period, the counter clocks the flip-flop, updating the output. Figure 2 shows the typical opening and closing switch debounce operation. On the MAX6818, the change output (\overline{CH}) is updated simultaneously with the switch outputs.

Undervoltage Lockout

The undervoltage-lockout circuitry ensures that the out-puts are at the correct state on power-up. While the supply voltage is below the undervoltage threshold (typically 1.9V), the debounce circuitry remains transparent. Switch states are present at the logic outputs with no debouce delay.

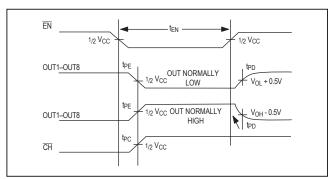


Figure 4. MAX6818 µP Interface Timing Diagram

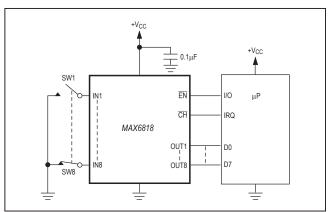


Figure 5. MAX6818 Typical µP Interfacing Circuit

±15kV ESD-Protected, Single/Dual/Octal, **CMOS Switch Debouncers**

Robust Switch Inputs

The switch inputs on the MAX6816-MAX6818 have overvoltage-clamping diodes to protect against damaging fault conditions. Switch input voltage scan safely swing ±25V to ground (Figure 3). Proprietary ESD-protection structures protect against high ESD encountered in harsh industrial environments, membrane keypads, and portable applications. They are designed to withstand ±15kV per the IEC 1000-4-2 Air-Gap Discharge Test and ±8kV per the IEC 1000-4-2 Contact Discharge Test.

Since there are $63k\Omega$ (typical) pullup resistors connected to each input, driving an input to -25V draws approximately 0.5mA (up to 4mA for eight inputs) from the V_{CC} supply. Driving an input to +25V will cause approximately 0.32mA of current (up to 2.6mA for eight inputs) to flow back into the V_{CC} supply. If the total system V_{CC} supply current is less than the current flowing back into the V_{CC} supply, V_{CC} will rise above normal levels.

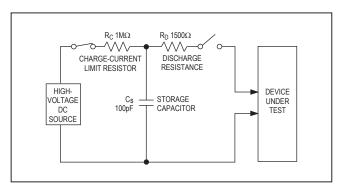


Figure 6a. Human Body ESD Test Model

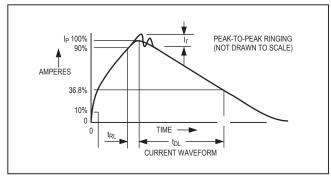


Figure 6b. Human Body Current Waveform

In some low-current systems, a zener diode on V_{CC} may be required.

±15kV ESD Protection

As with all Maxim devices, ESD-protection structures are incorporated on all pins to protect against electrostatic discharges encountered during handling and assembly. The MAX6816-MAX6818 have extra protection against static electricity. Maxim's engineers have developed state-ofthe-art structures to protect against ESD of ±15kV at the switch inputs without damage. The ESD structures withstand high ESD in all states: normal operation, shutdown, and powered down. After an ESD event, the MAX6816-MAX6818 keep working without latchup, whereas other solutions can latch and must be powered down to remove latchup.

ESD protection can be tested in various ways; these products are characterized for protection to the following limits:

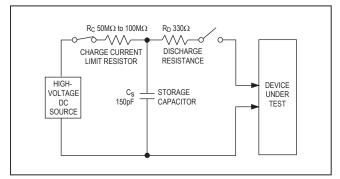


Figure 7a. IEC 1000-4-2 ESD Test Model

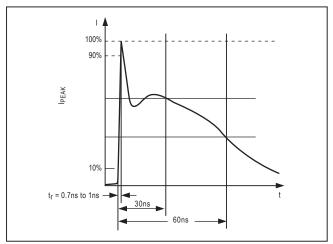


Figure 7b. IEC 1000-4-2 ESD Generator Current Waveform

±15kV ESD-Protected, Single/Dual/Octal, CMOS Switch Debouncers

- 1) ±15kV using the Human Body Model
- ±8kV using the Contact-Discharge method specified in IEC 1000-4-2
- 3) ±15kV using IEC 1000-4-2's Air-Gap method.

ESD Test Conditions

ESD performance depends on a variety of conditions. Contact Maxim for a reliability report that documents test setup, test methodology, and test results.

Human Body Model

Figure 6a shows the Human Body Model and Figure 6b shows the current waveform it generates when discharged into a low impedance. This model consists of a 100pF capacitor charged to the ESD voltage of interest, which is then discharged into the test device through a $1.5 k\Omega$ resistor.

IEC 1000-4-2

The IEC 1000-4-2 standard covers ESD testing and performance of finished equipment; it does not specifically refer to integrated circuits. The MAX6816–MAX6818 help you design equipment that meets Level 4 (the highest level) of IEC 1000-4-2, without the need for additional ESD-protection components.

The major difference between tests done using the Human Body Model and IEC 1000-4-2 is higher peak current in IEC 1000-4-2, because series resistance is lower in the IEC 1000-4-2 model. Hence, the ESD withstand voltage measured to IEC 1000-4-2 is generally lower than that measured using the Human Body Model. Figure 7a shows the IEC 1000-4-2 model and Figure 7b shows the current waveform for the 8kV, IEC 1000-4-2, Level 4, ESD Contact-Discharge test.

The Air-Gap test involves approaching the device with a charged probe. The Contact-Discharge method connects the probe to the device before the probe is energized.

Machine Model

The Machine Model for ESD tests all pins using a 200pF storage capacitor and zero discharge resistance. Its objective is to emulate the stress caused by contact that occurs with handling and assembly during manufacturing.

MAX6818 µP Interfacing

The MAX6818 has an output enable (\overline{EN}) input that allows switch outputs to be three-stated on the μP data bus until polled by the μP . Also, state changes at the switch inputs are detected, and an output (\overline{CH}) goes low after the debounce period to signal the μP . Figure 4 shows the timing diagram for enabling outputs and reading data. If the output enable is not used, tie \overline{EN} to GND to "always enable" the switch outputs. If \overline{EN} is low, \overline{CH} is always high. If a change of state is not required, leave \overline{CH} unconnected.

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Chip Information

SUBSTRATE CONNECTED TO GND PROCESS: BICMOS

Package Information

For the latest package outline information and land patterns (footprints), go to www.maximintegrated.com/packages. Note that a "+", "#", or "-" in the package code indicates RoHS status only. Package drawings may show a different suffix character, but the drawing pertains to the package regardless of RoHS status.

PACKAGE TYPE	PACKAGE CODE	OUTLINE NO.	LAND PATTERN NO.
4 SOT143	U4-1	21-0052	<u>90-0183</u>
6 SOT23	U6-4	<u>21-0058</u>	<u>90-0175</u>
20 SSOP	A20-1	<u>21-0056</u>	90-0094

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Revision History

REVISION NUMBER	REVISION DATE	DESCRIPTION	PAGES CHANGED
0	7/98	Initial release	_
3	8/10	Updated Ordering Information, Electrical Characteristics, Typical Operating Characteristics, and the Undervoltage Lockout section.	1–4, 7
4	7/14	No /V OPNs; removed automotive reference from Applications section	1
5	4/15	Updated Benefits and Features section	1
6	2/19	Updated Ordering Information, Absolute Maximum Ratings, and Electrical Characteristics	1, 2
7	7/19	Updated Ordering Information	1
8	2/20	Updated Ordering Information	1

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